

**REMARKS**

At the outset, the Examiner is thanked for the thorough review and consideration of the pending application. The Office Action dated September 30, 2005, has been received and its contents carefully reviewed.

Claims 1-8 are withdrawn in this application. Claims 9-22 are rejected to by the Examiner. Claim 9 has been amended. Claims 1-22 remain pending in this application.

In the Office Action, claims 9-13, 18, 19, 21 and 22 are rejected under 35 U.S.C. § 102(e) as being anticipated by U.S. Publication No. 2002/0004108 to Iwakabe et al. (hereinafter "Iwakabe"). Claims 14-17 and 20 are rejected under 35 U.S.C. § 103(a) as being unpatentable over Iwakabe in view of Admitted Related Art (hereinafter "ARA") and U.S. Patent No. 6,268,289 to Chowdhury (hereinafter "Chowdhury").

The rejection of claims 9-22 is respectfully traversed and reconsideration is requested. Claims 9-22 are allowable over the cited references in that each of these claims recite a combination of elements including, for example, "forming a silicide layer on the metal line in direct contact with at least a first surface portion of the metal line and the silicide layer is formed in a different layer from the metal line." Iwakabe does not teach or suggest at least this feature of the claimed invention.

The Examiner states that an electroconductive film d1 and a source electrode SD1 of Iwakabe correspond to a metal line and a silicide layer as recited in claim 9 of the present invention, respectively. In the present invention, the silicide layer is formed in a different layer from the metal line. In contrast to the present invention, wherein the silicide layer is formed in a different layer from the metal line, in Iwakabe, the electroconductive film d1 made of a metal silicide is formed in the same layer/material as the source electrode SD1 as shown in FIG. 15 and described in paragraphs [0142] and [0245]. Specifically, in Iwakabe, the source electrode SD1 is formed of the electroconductive film d1 by etching the electroconductive film d1. Therefore Iwakabe fails to teach at least this feature of the present invention. Further, the ARA and Chowdhury fail to cure this deficiency of Iwakabe. Accordingly, Applicant respectfully submits that claims 9-22 are allowable over the cited references.

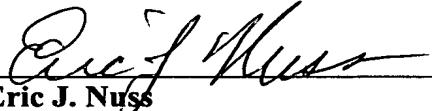
Applicants believe the foregoing amendments place the application in condition for allowance and early, favorable action is respectfully solicited.

If for any reason the Examiner finds the application other than in condition for allowance, the Examiner is requested to call the undersigned attorney at (202) 496-7500 to discuss the steps necessary for placing the application in condition for allowance. All correspondence should continue to be sent to the below-listed address.

If these papers are not considered timely filed by the Patent and Trademark Office, then a petition is hereby made under 37 C.F.R. § 1.136, and any additional fees required under 37 C.F.R. § 1.136 for any necessary extension of time, or any other fees required to complete the filing of this response, may be charged to Deposit Account No. 50-0911. Please credit any overpayment to deposit Account No. 50-0911. *A duplicate copy of this sheet is enclosed.*

Respectfully submitted,

Dated: January 30, 2006

By   
Eric J. Nuss  
Registration No. 40,106

McKENNA LONG & ALDRIDGE LLP  
1900 K Street, N.W.  
Washington, DC 20006  
(202) 496-7500  
Attorneys for Applicant